Amendments to the Claims

1-18 (Cancelled).

19. (Previously Presented) An electronic module, the module comprising:

an insulating-material layer, which has a first surface and a second surface;

at least one hole or recess in the insulating-material layer, which opens out onto the first surface;

at least one component inside the at least one hole or recess, wherein the component includes contact zones on the side of the component that faces the first surface of the insulating-material layer, and further wherein the component is positioned in such a way that the contact zones are located at a specified distance from the level of the first surface of the insulating-material layer;

a conductive-pattern layer, which runs on the first surface of the insulating-material layer and extends on top of the at least one hole or recess in the insulating-material layer and at the location of the contact zones of the components;

a hardened adhesive layer in the hole or recess in the insulating-material layer, between the component and the conductive-pattern layer; and

an electrical contact area between the conductive-pattern layer and the contact zones of the component, where said contact area is formed by conductive-material formations penetrating the adhesive layer.

20. (Previously Presented) The electronic module according to Claim 19, wherein the thickness of the component is less than the thickness of the insulating-material layer in the direction between the first surface and the second surface of the insulating-material layer.

21. (Previously Presented) The electronic module according to Claim 19, wherein the conductive-pattern layer is substantially flat, so that the surface of the conductive-pattern layer that lies against the insulating-material layer, and the hole or recess in the insulating-material layer for the component, is located entirely at substantially the level of the first surface of the

insulating-material layer.

22. (Previously Presented) The electronic module according to Claim 19, further comprising a second conductive-pattern layer, which runs on the second surface of the insulating-material layer.

23. (Previously Presented) The electronic module according to Claim 19, further comprising several components connected electrically to each other by conductive patterns, such that the components form a functional totality.

24. (Previously Presented) The electronic module according to Claim 22, wherein the insulating-material layer is a unified and tight layer of polymer between the conductive-pattern layer and the second conductive-pattern layer and around the at least one component.

25. (Previously Presented) The electronic module according to Claim 24, wherein the polymer is epoxy.

26. (Previously Presented) The electronic module according to Claim 25, wherein the insulating-material layer includes at least one layer of glass-fibres inside the layer of epoxy.

27. (Previously Presented) The electronic module according to Claim 26, wherein at least one of said at least one layer of glass-fibres comprises a hole made for the at least one component.

28. (Previously Presented) The electronic module according to Claim 26, wherein at least one of said at least one layer of glass-fibres extends between the at least one component and the second conductive-pattern layer.

29. (Previously Presented) The electronic module according to Claim 19, wherein the

insulating-material layer comprises at least one glass-fibre mat and a layer of epoxy tightly surrounding said at least one component and said at least one glass-fibre mat.

30. (Previously Presented) The electronic module according to Claim 19, wherein the insulating-material layer comprises epoxy and at least one glass-fibre mat having at least one hole for the at least one component.

31. (Previously Presented) The electronic module according to Claim 30, wherein the at least one component is located in the at least one hole in the glass-fibre mat and the epoxy fills the at least one hole in the glass-fibre mat around the component.

32. (Previously Presented) The electronic module according to Claim 30, wherein the epoxy forms a unified layer fastening the at least one glass-fibre mat and the at least one component in the electronic module.